

2025 RELEASE UNDER E.O. 14176

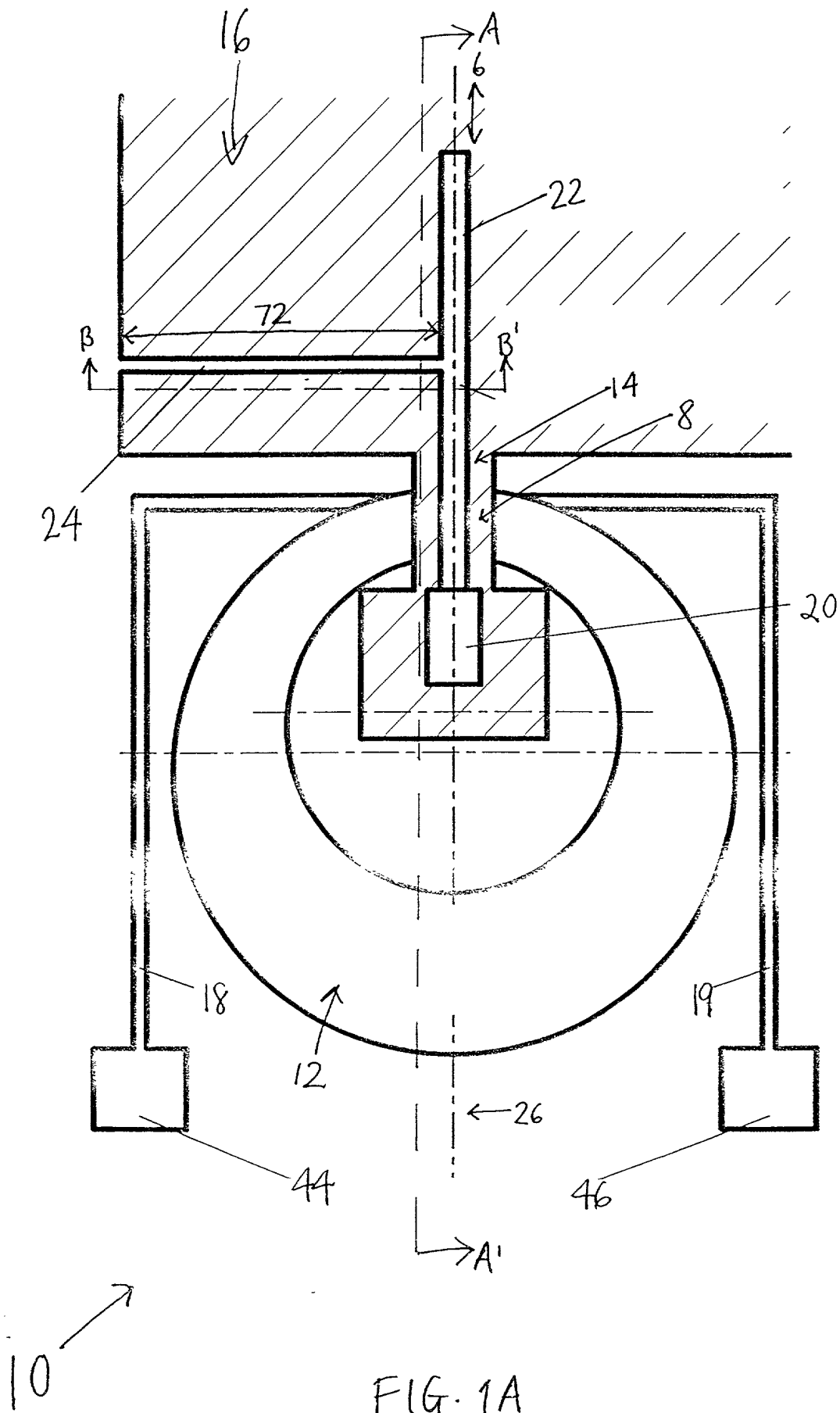


FIG. 1B

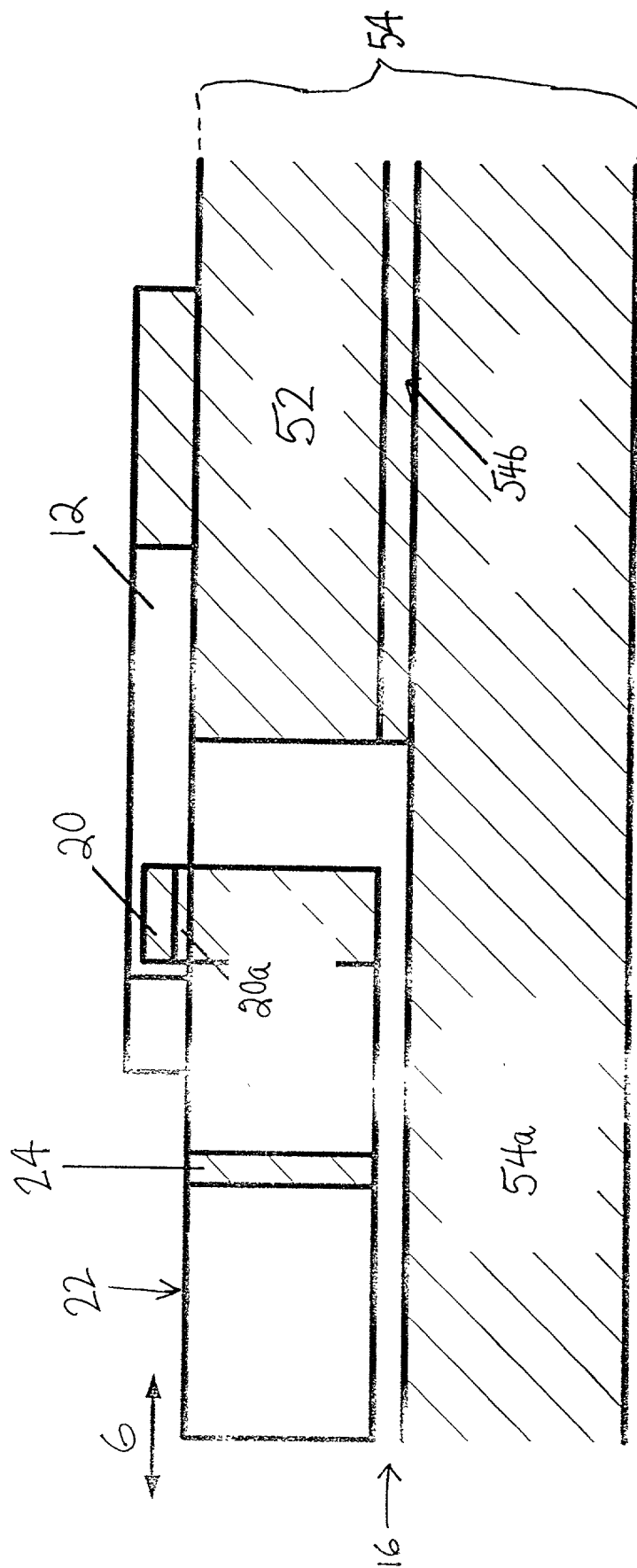


FIG. 1C

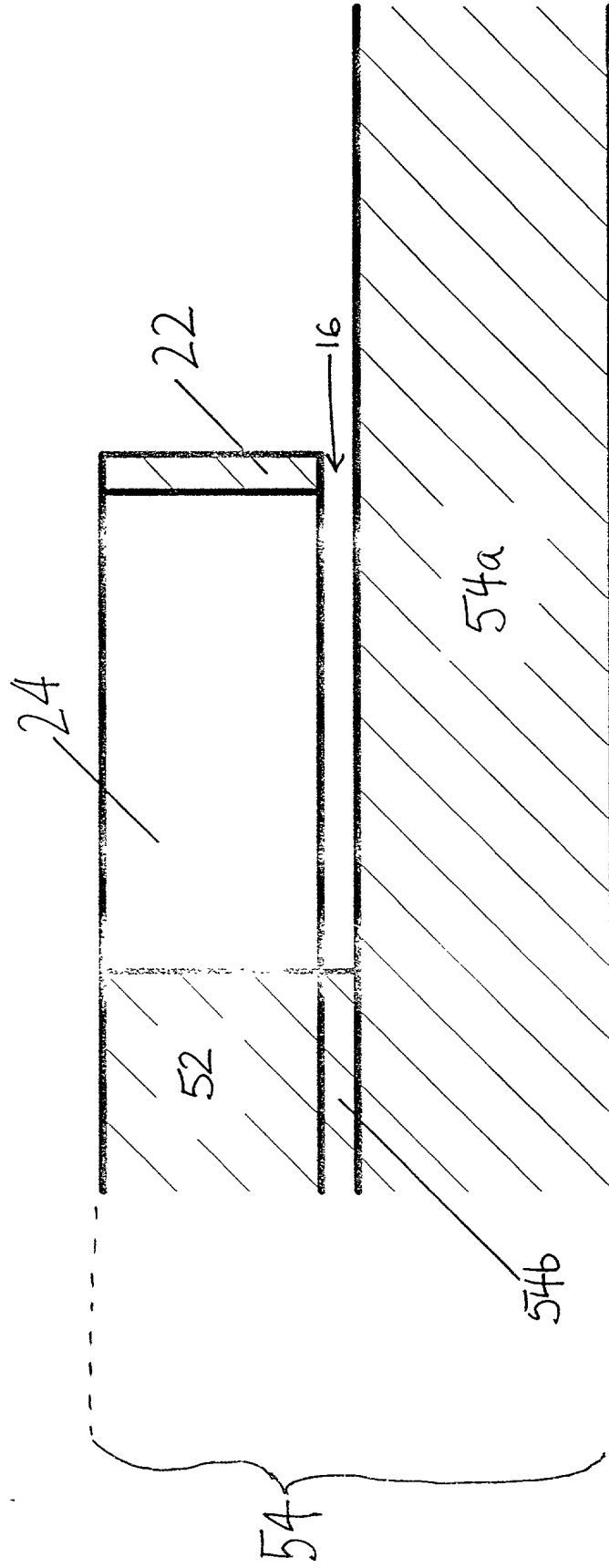
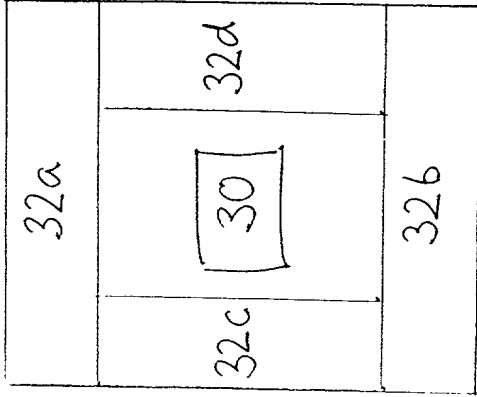


FIG. 2B



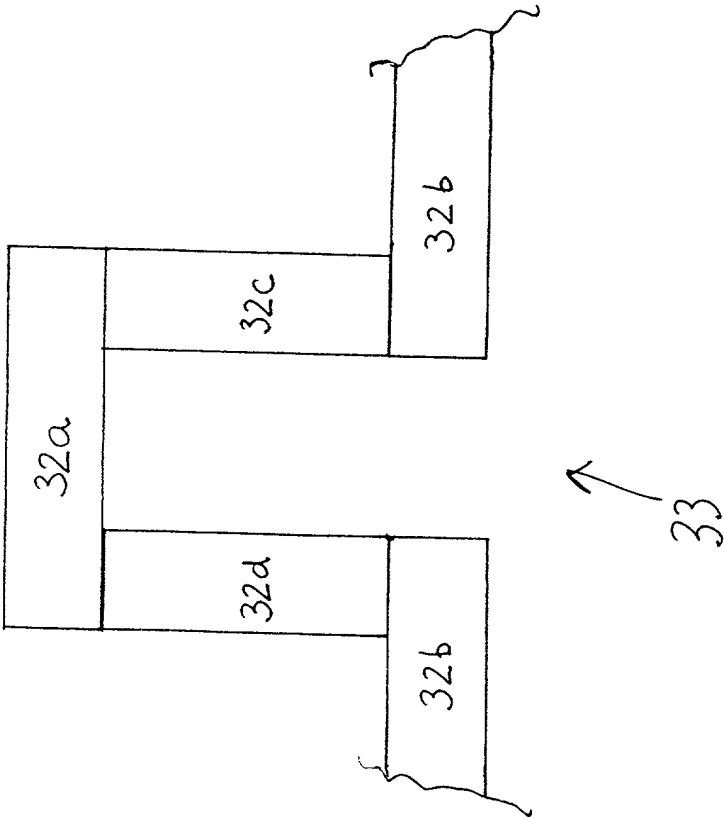


FIG. 20

FIG. 2D

10079985.022107

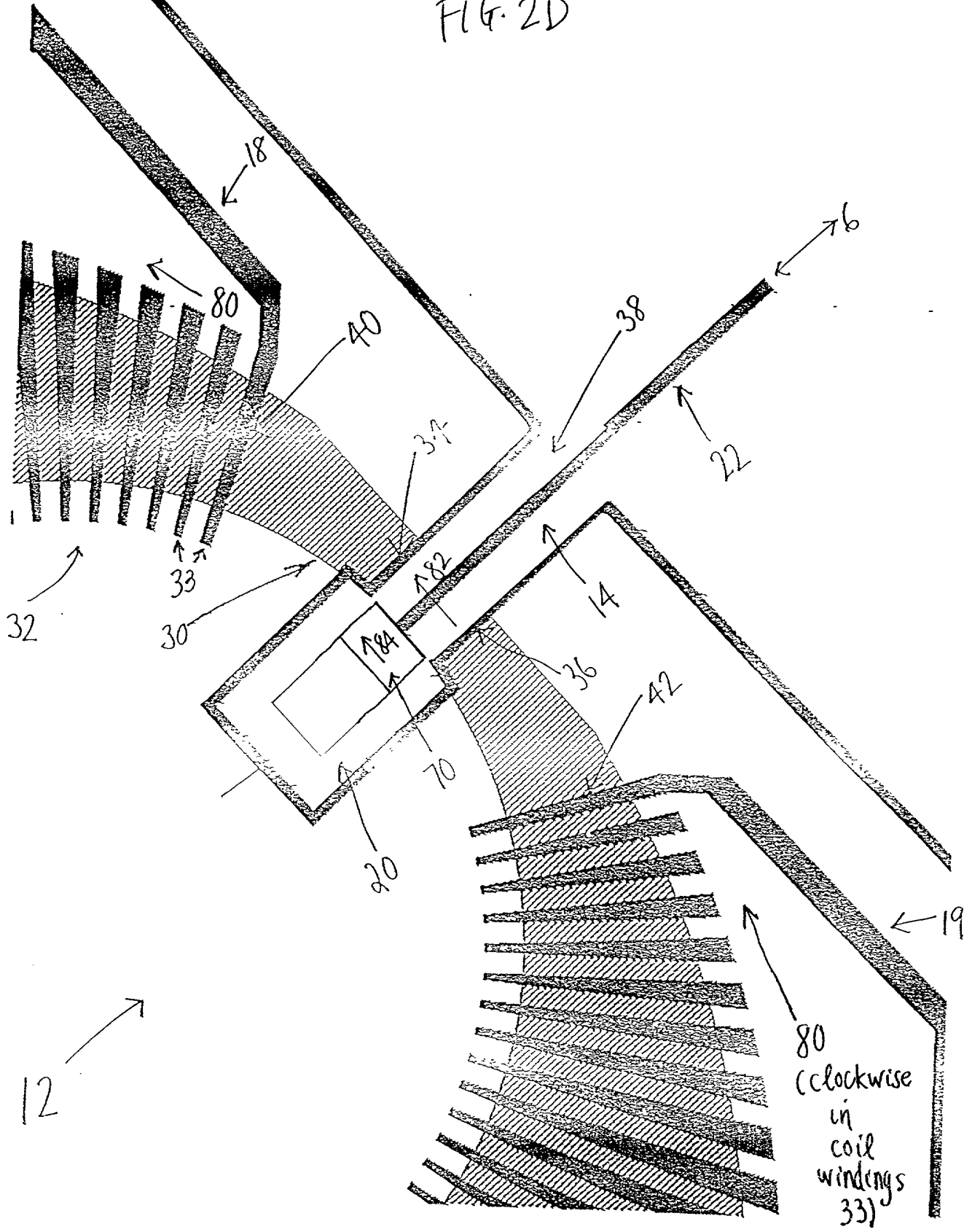
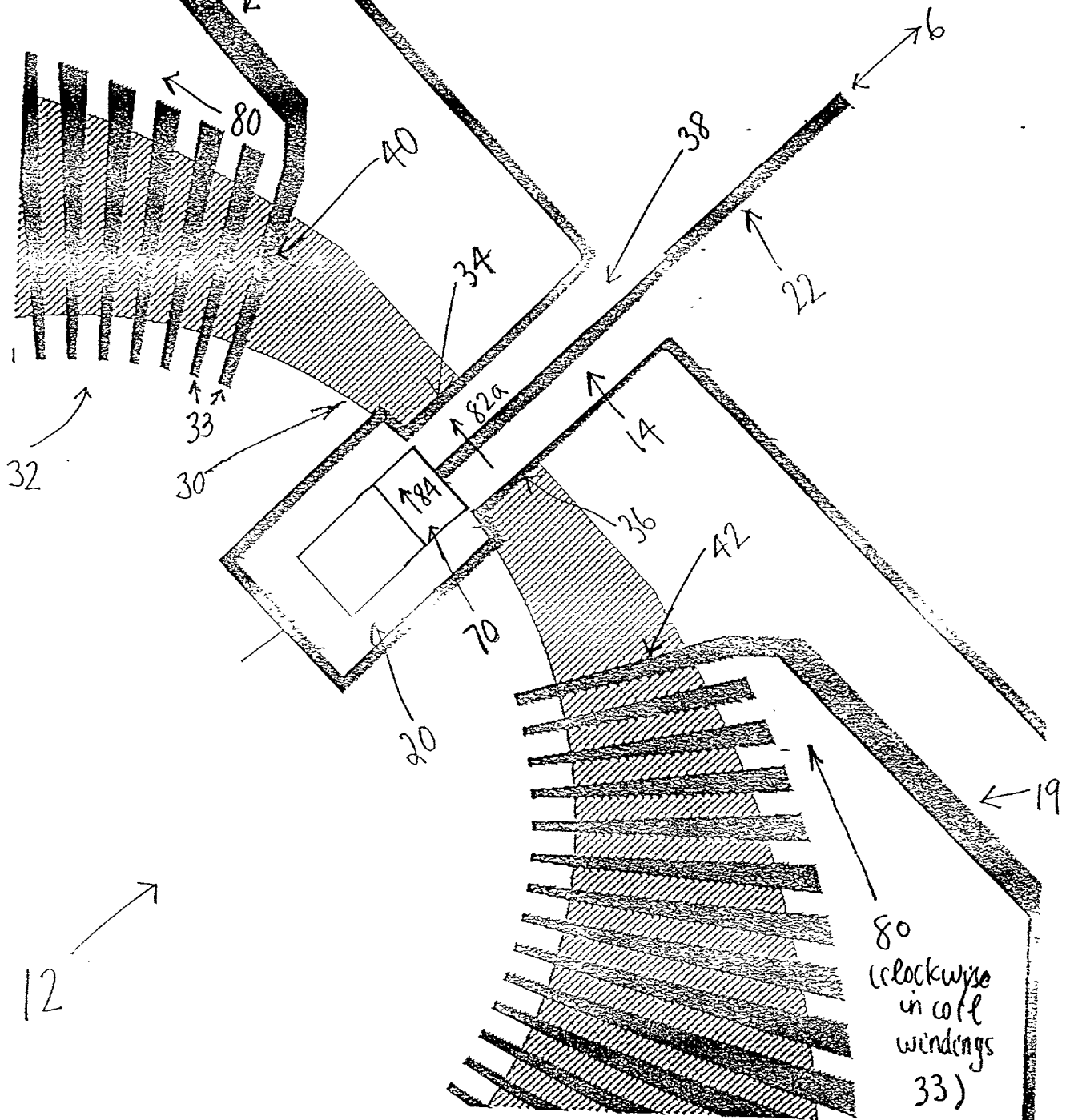
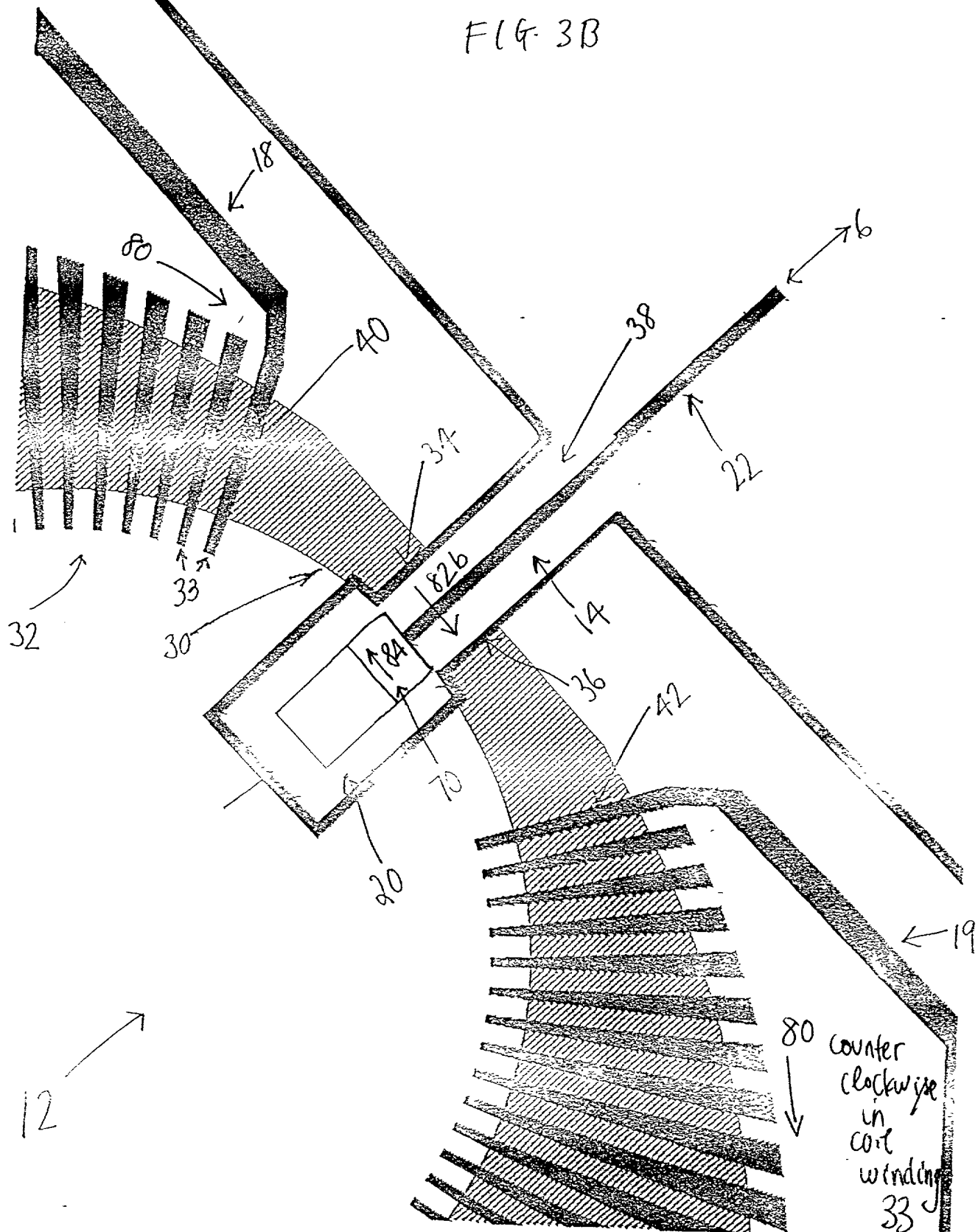


FIG. 3A

10079985-02202



[illegible]

2012-2013

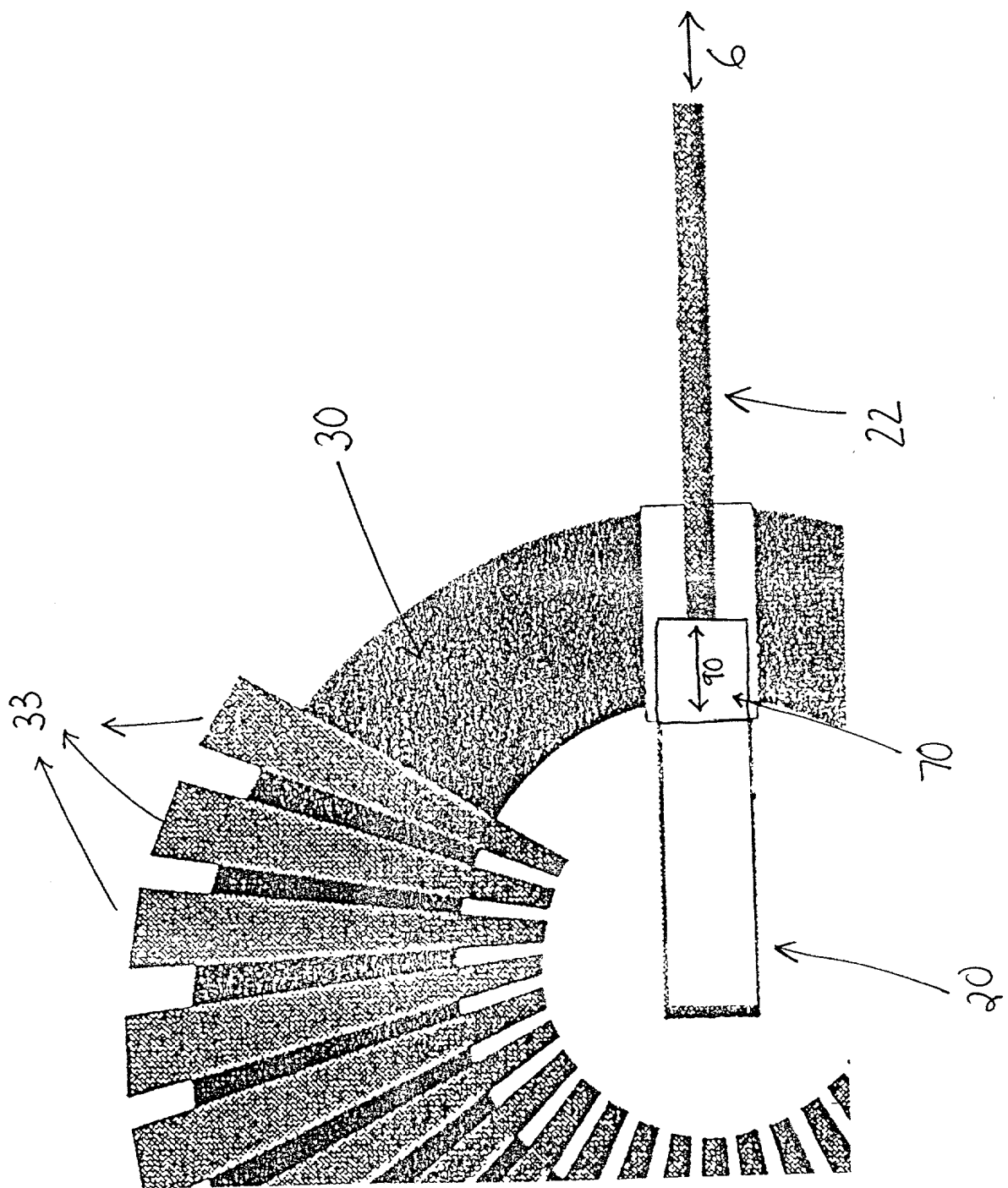


Fig. 4A

12

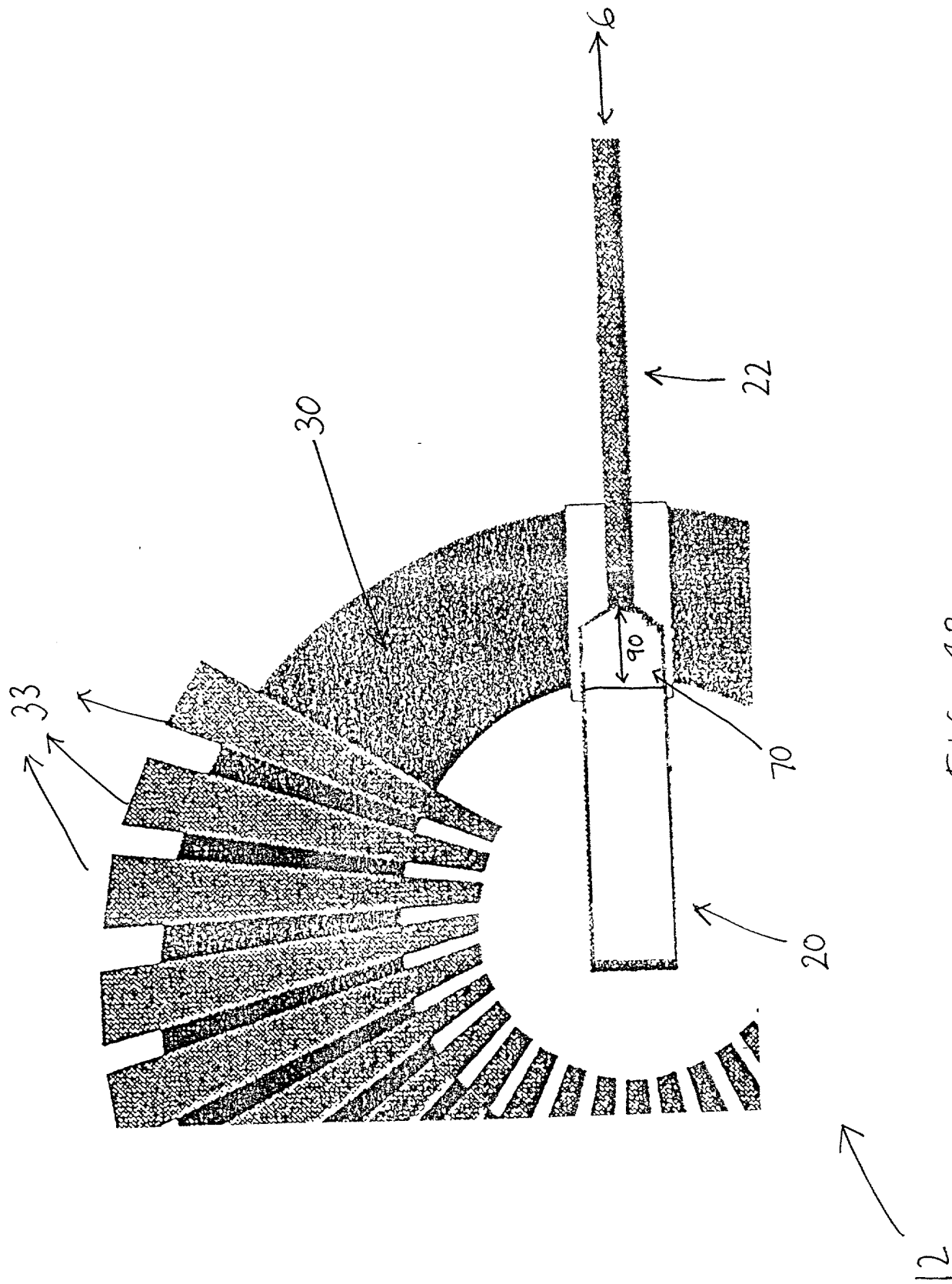
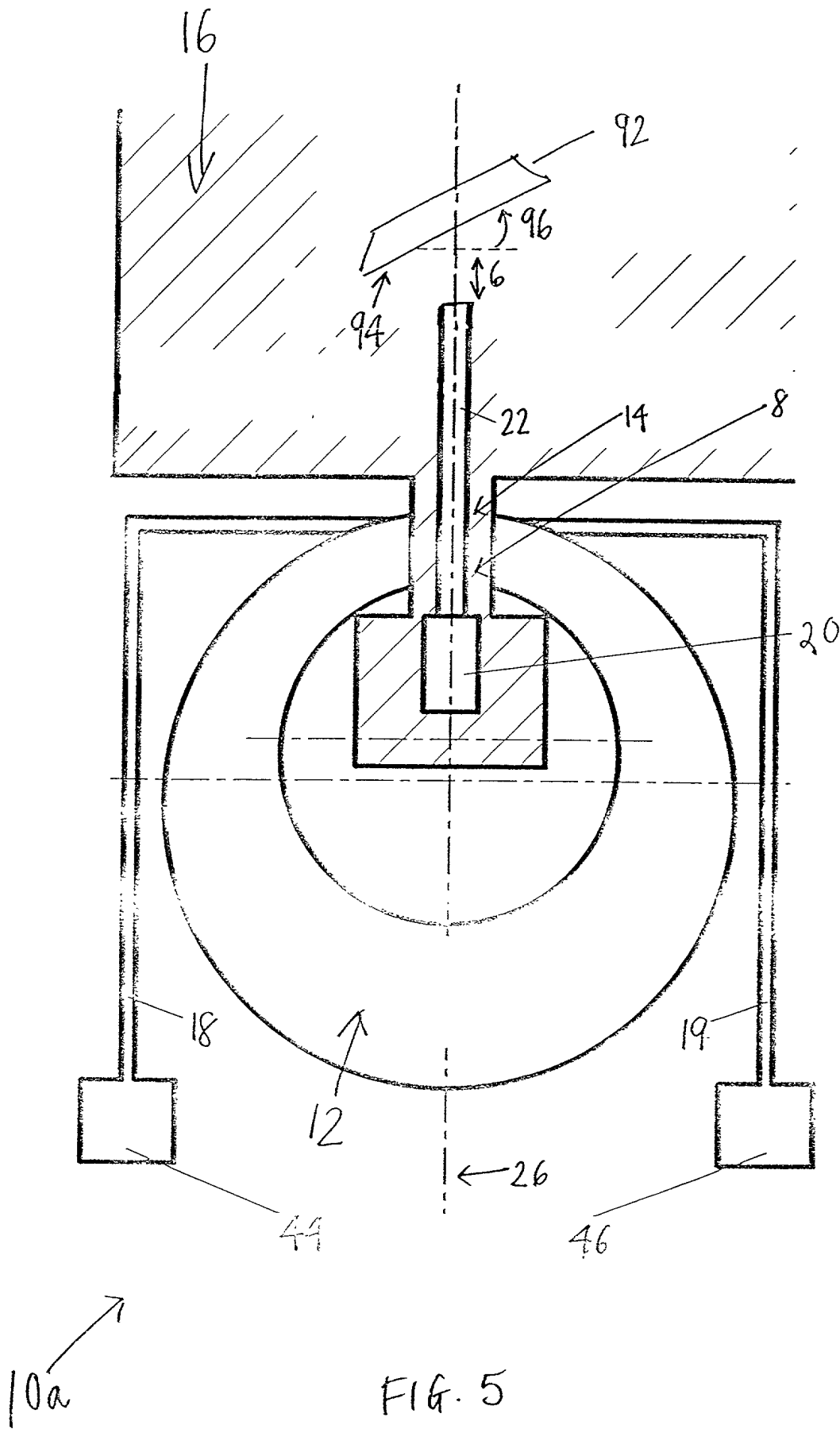


FIG. 4B

20120159862001



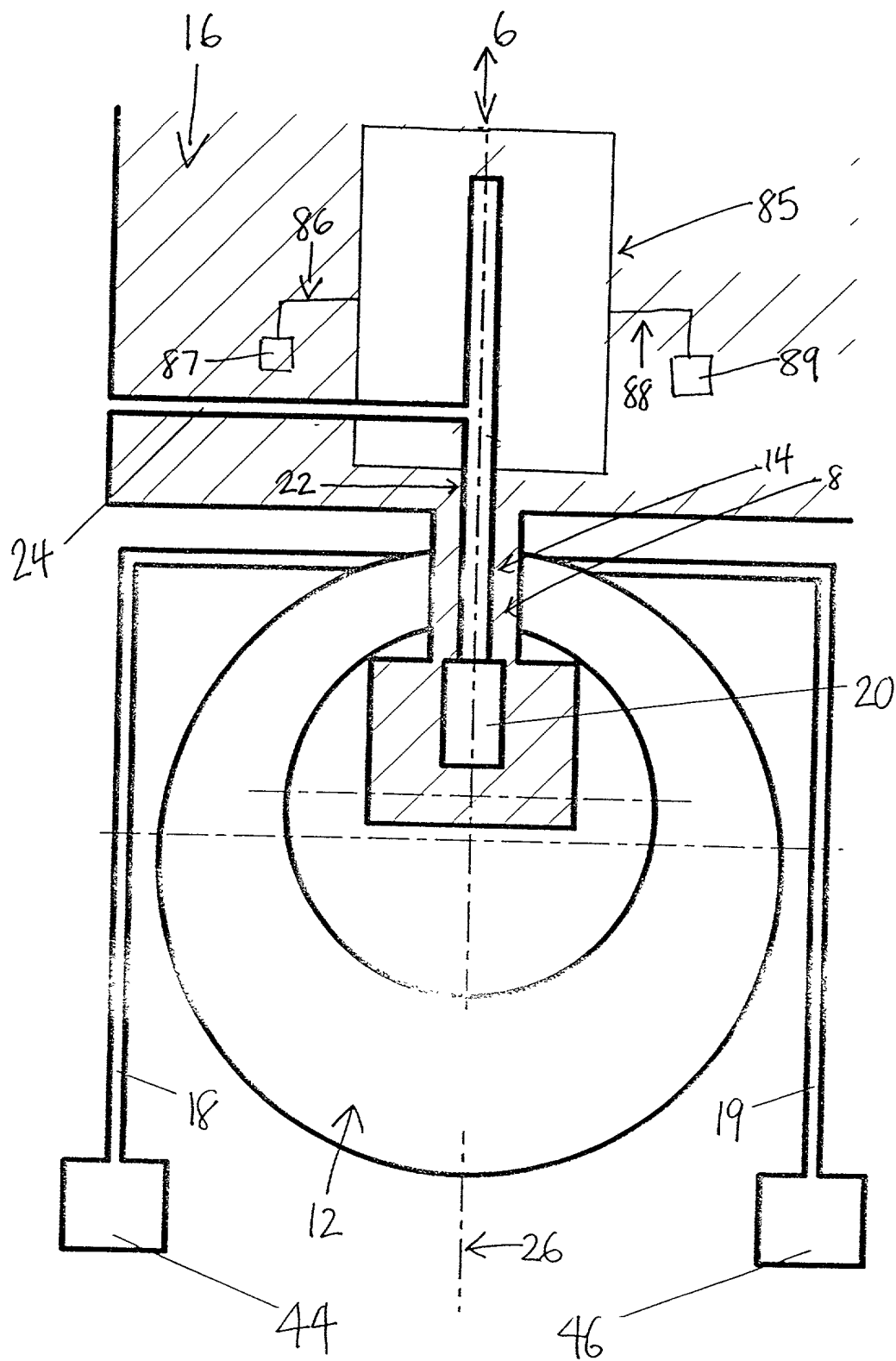
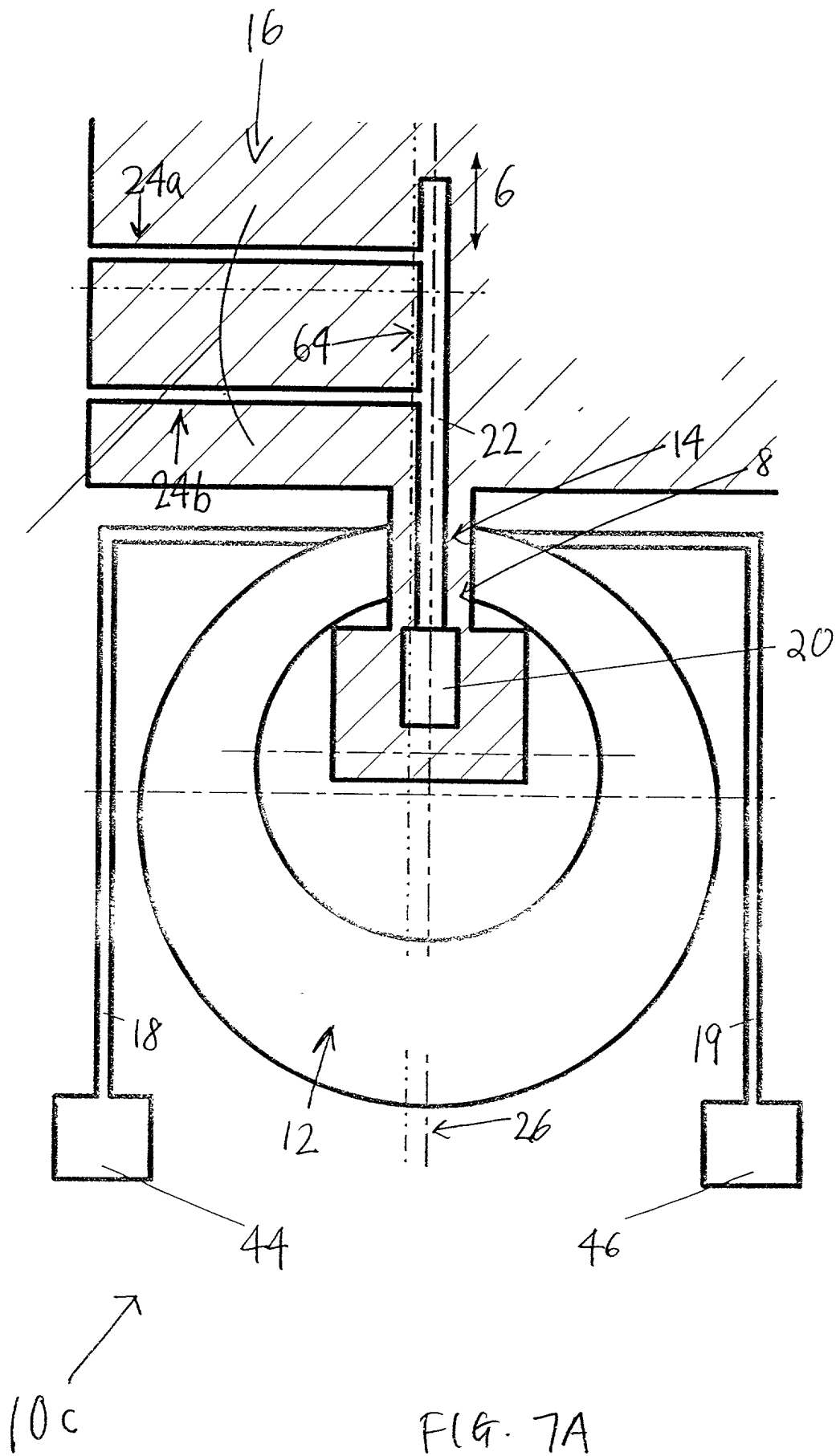
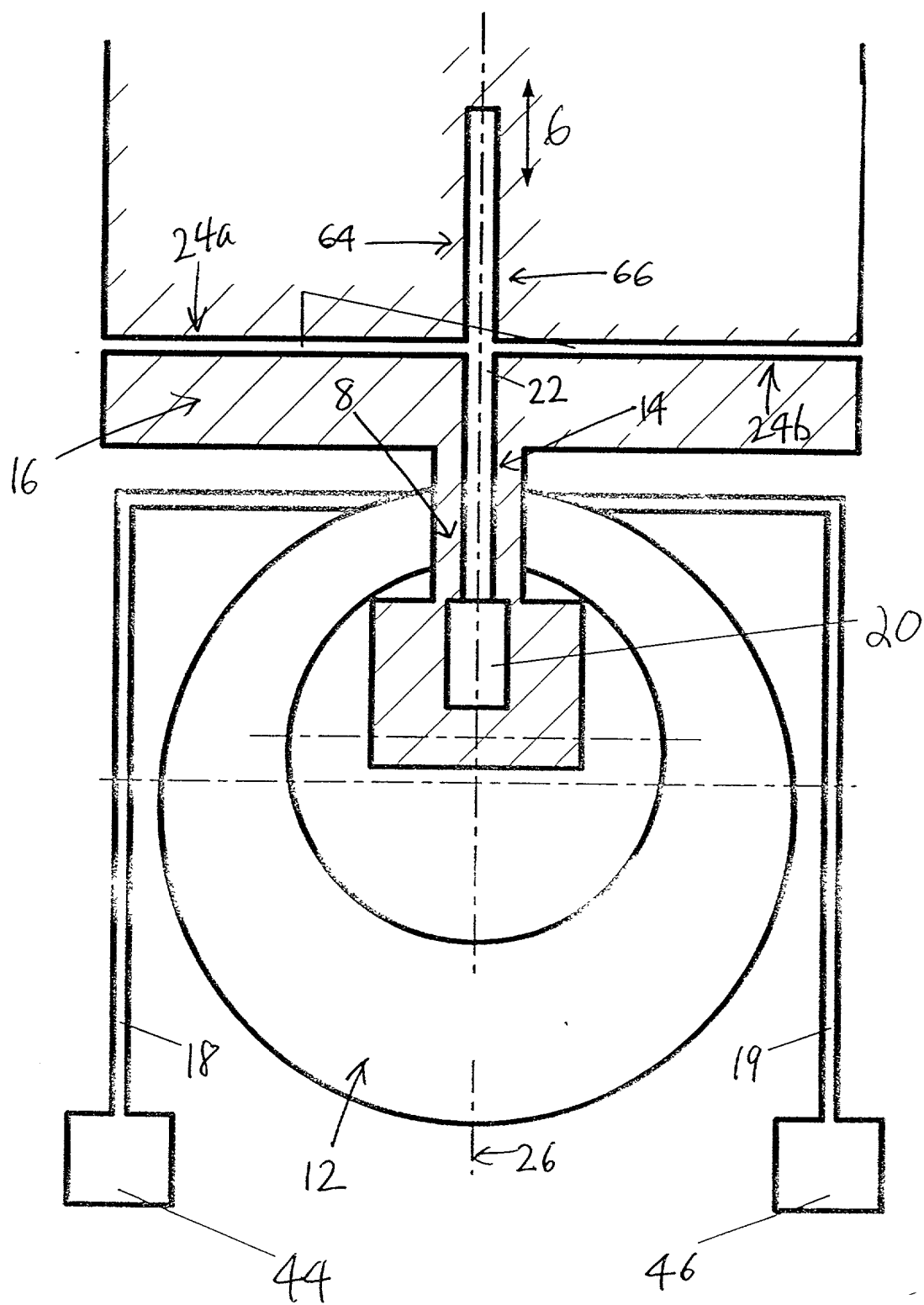


FIG. 6

10079986-022102

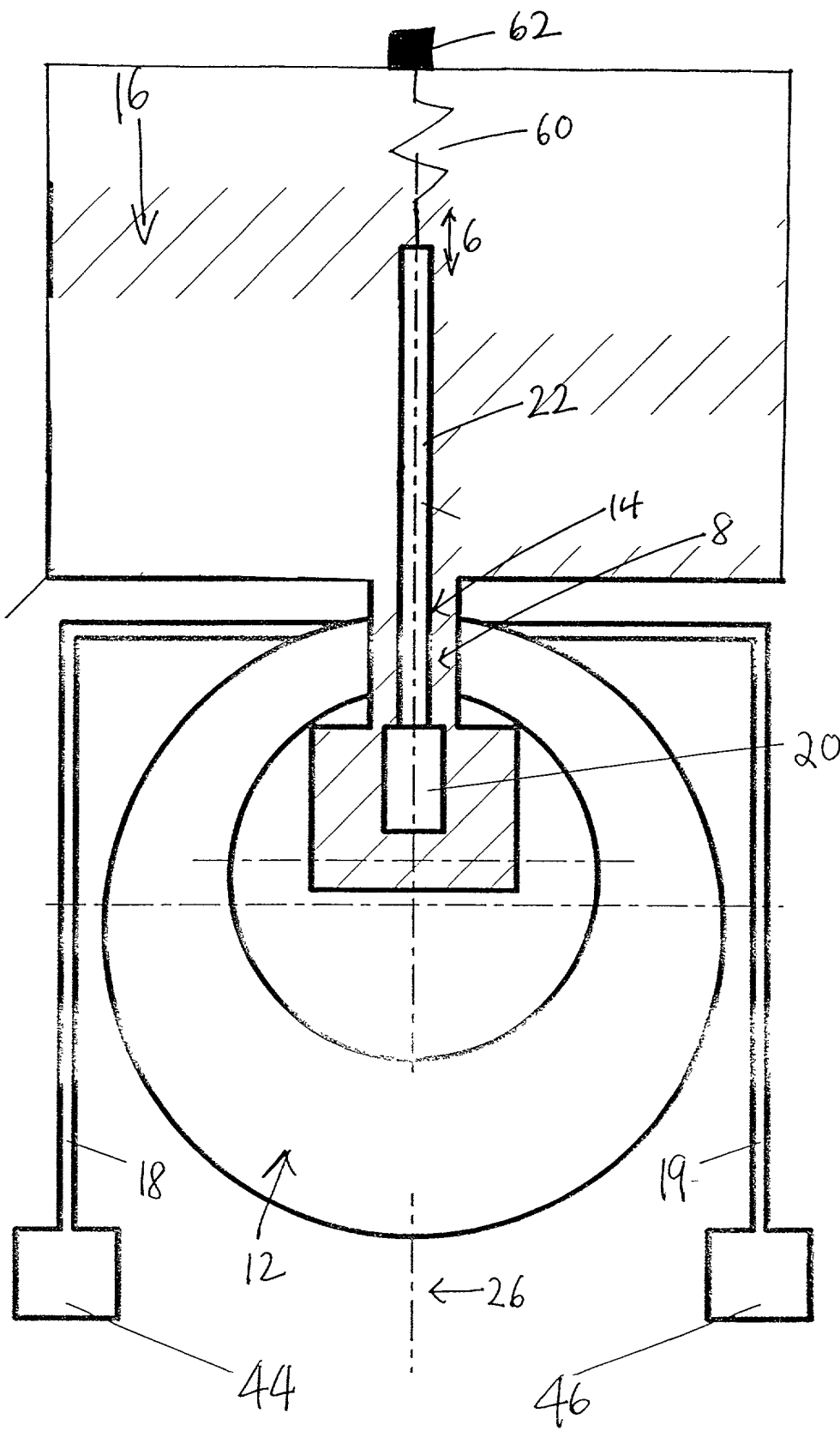


2022075866001

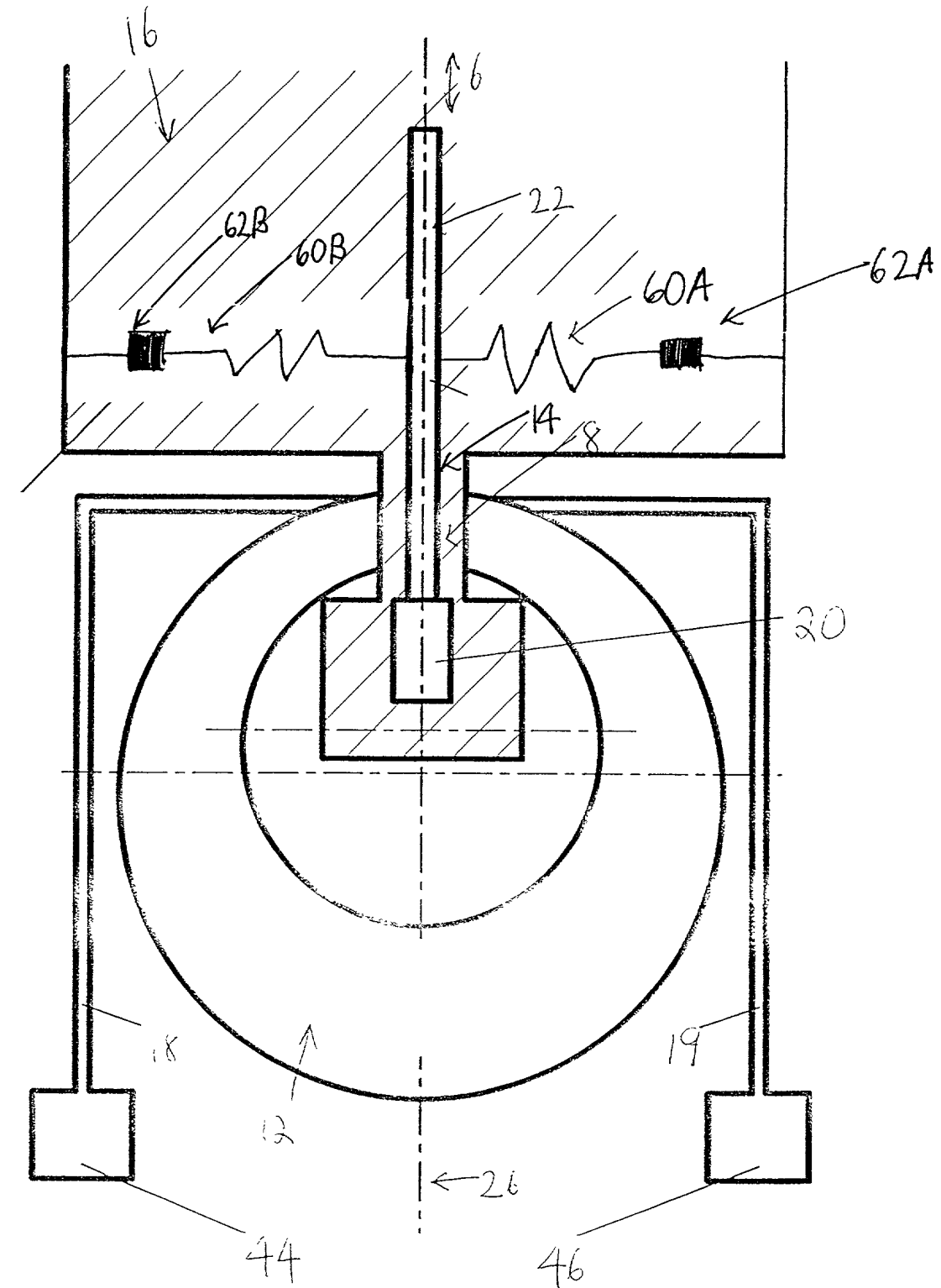


10d

FIG. 7B



10079986, 024100



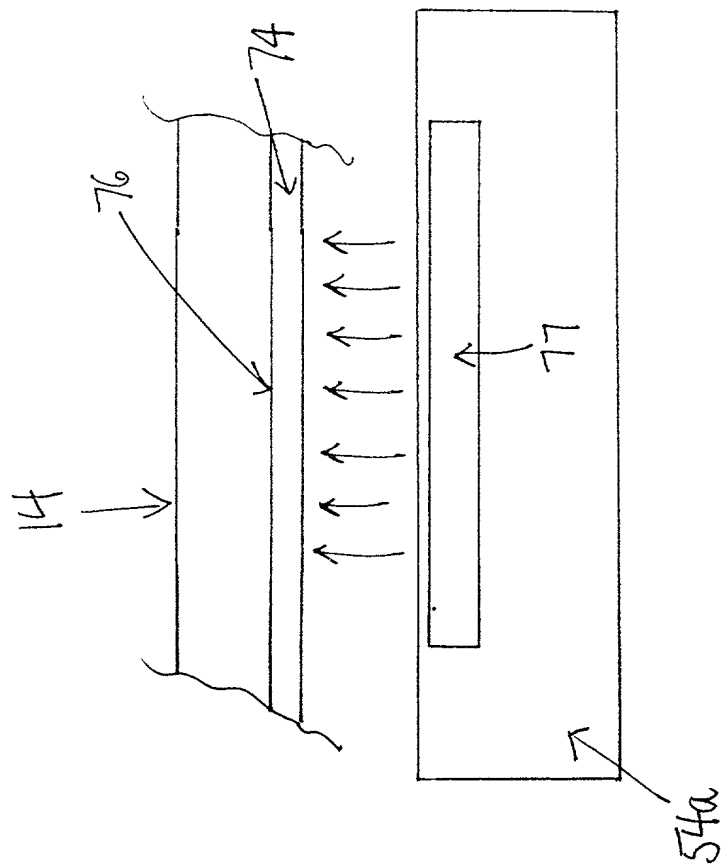


FIG. 9A

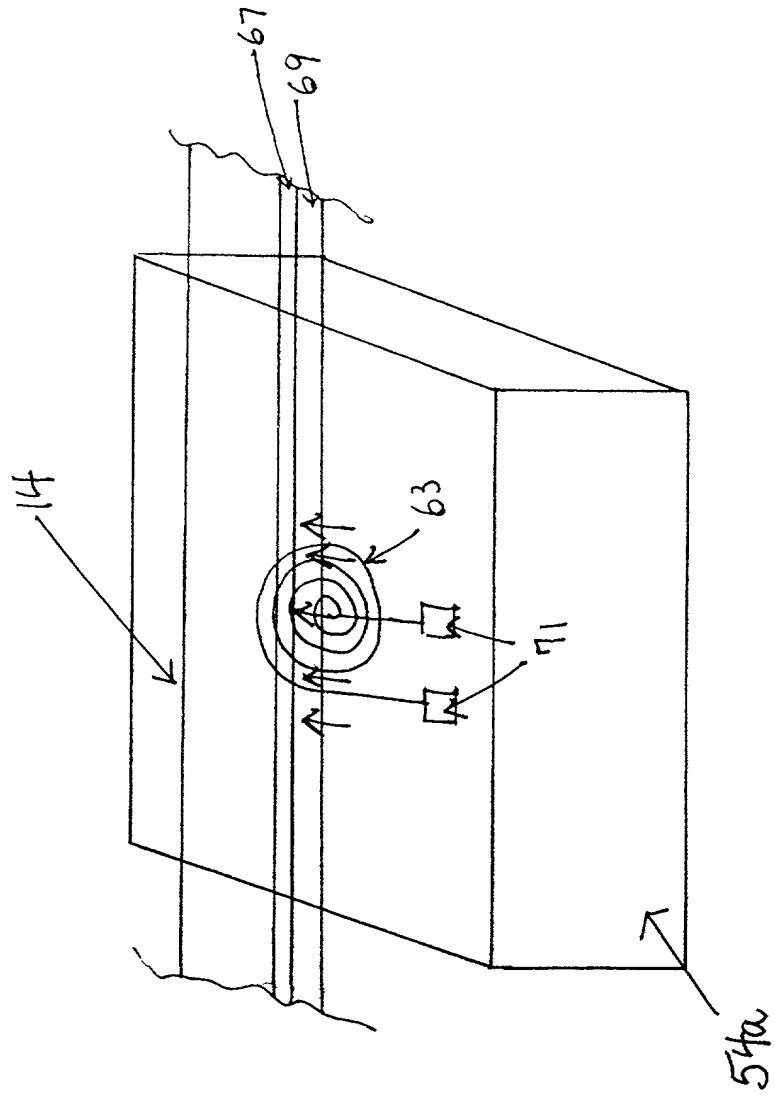


FIG. 9B

FIG. 10

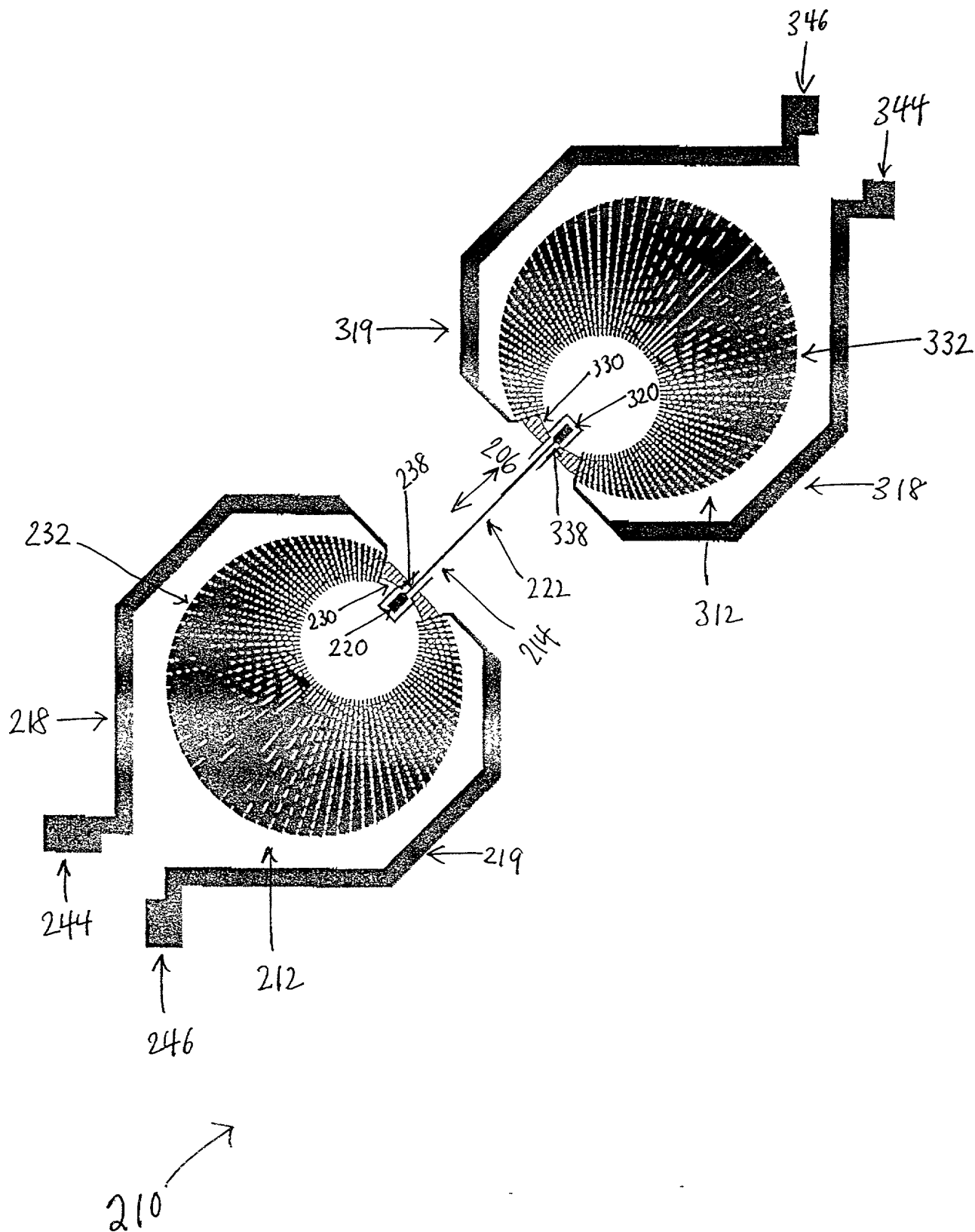


FIG. 11

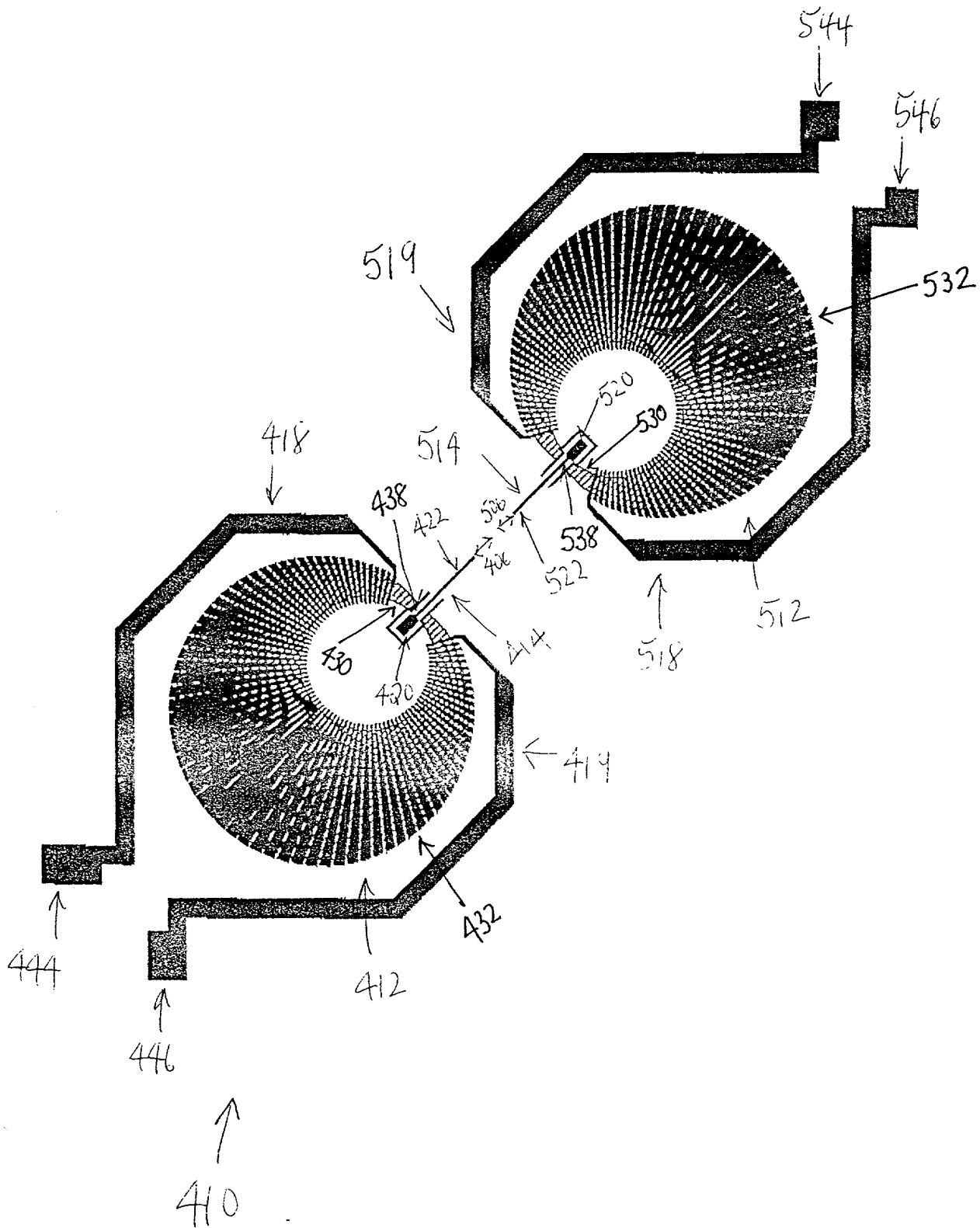
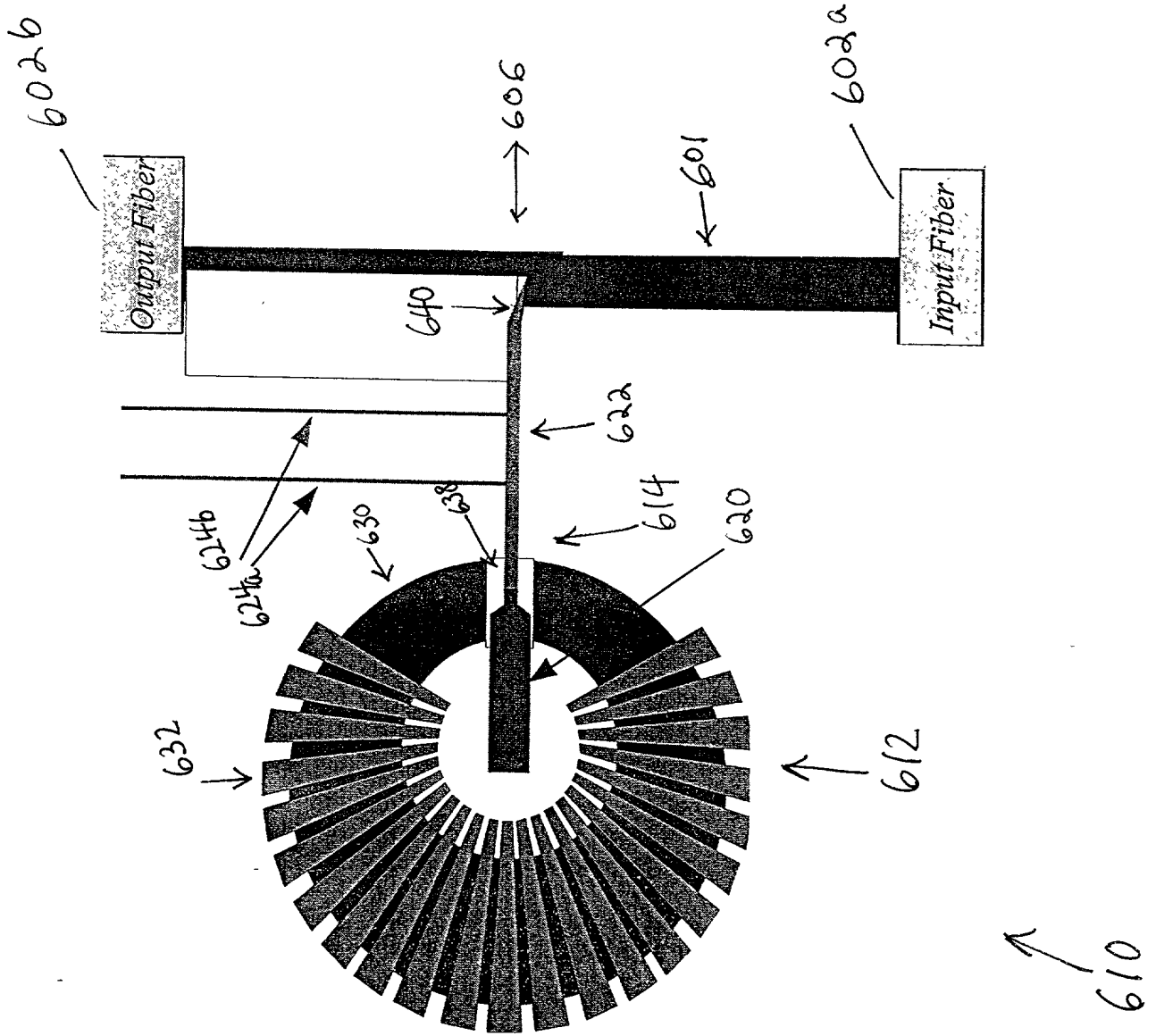
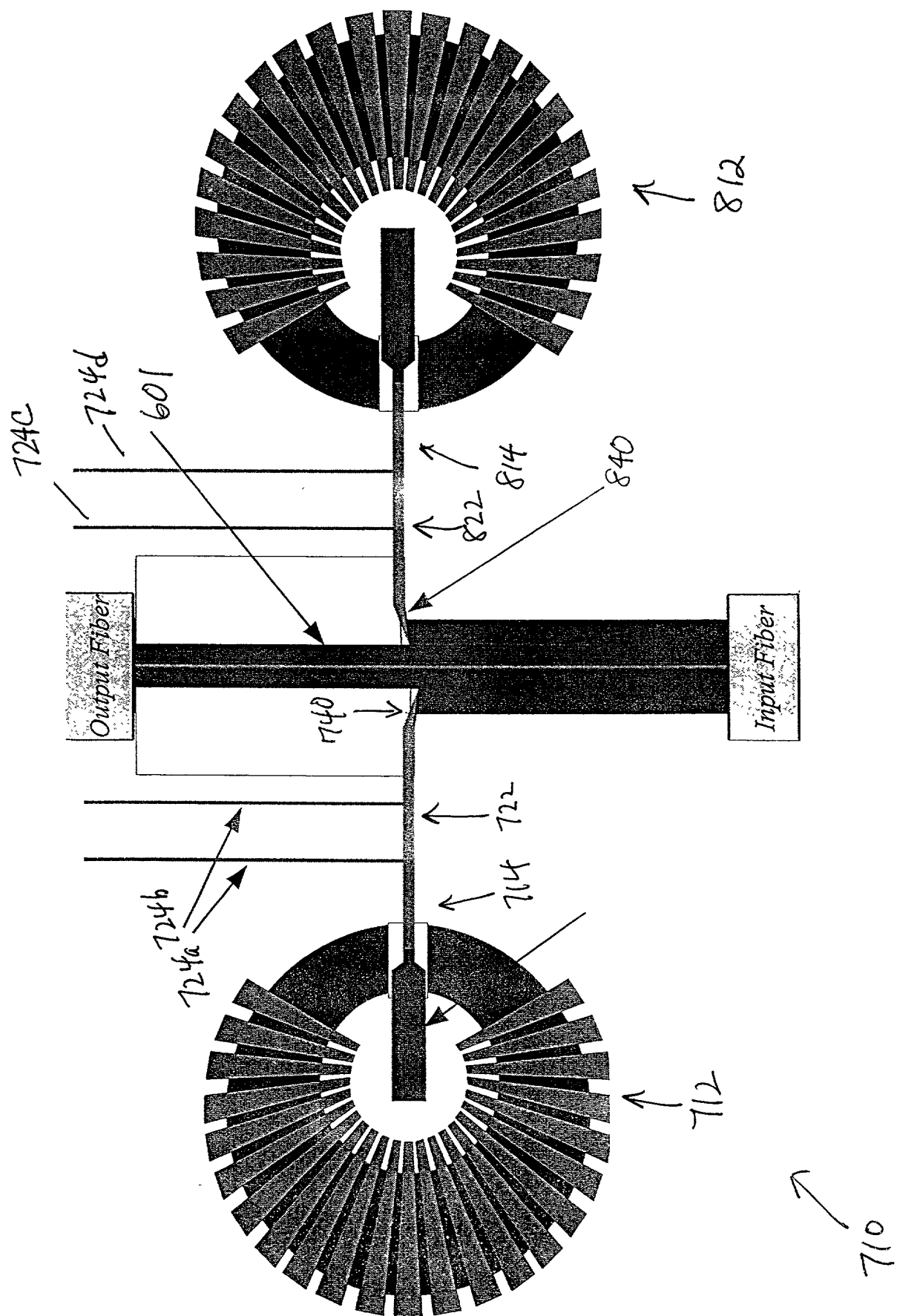


FIG. 12a





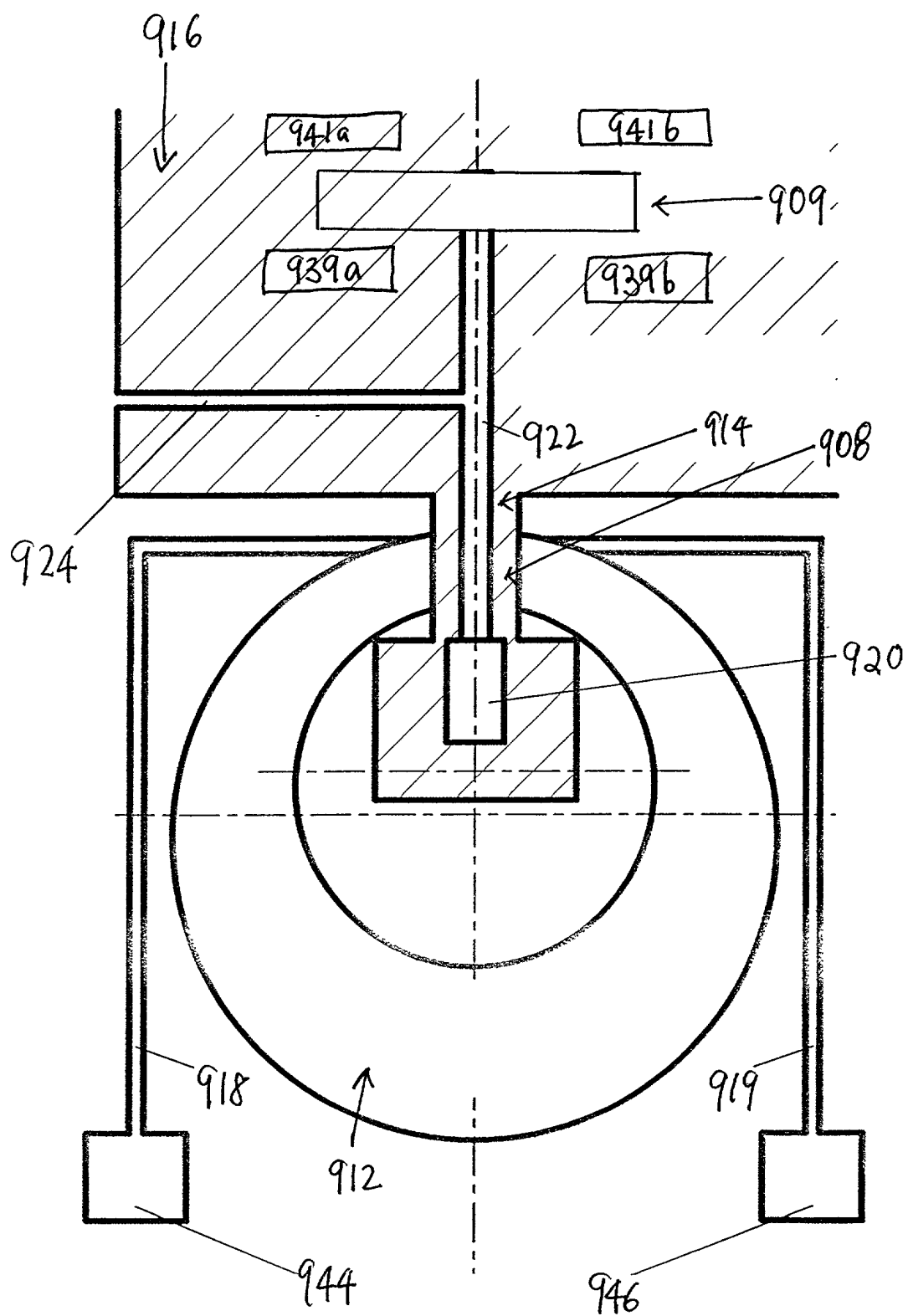


FIG. 14

1010 ↗

FIG. 15A

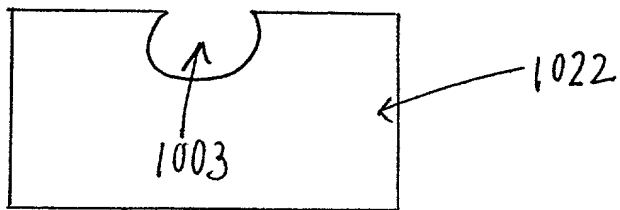


FIG. 15B

FIG. 16A

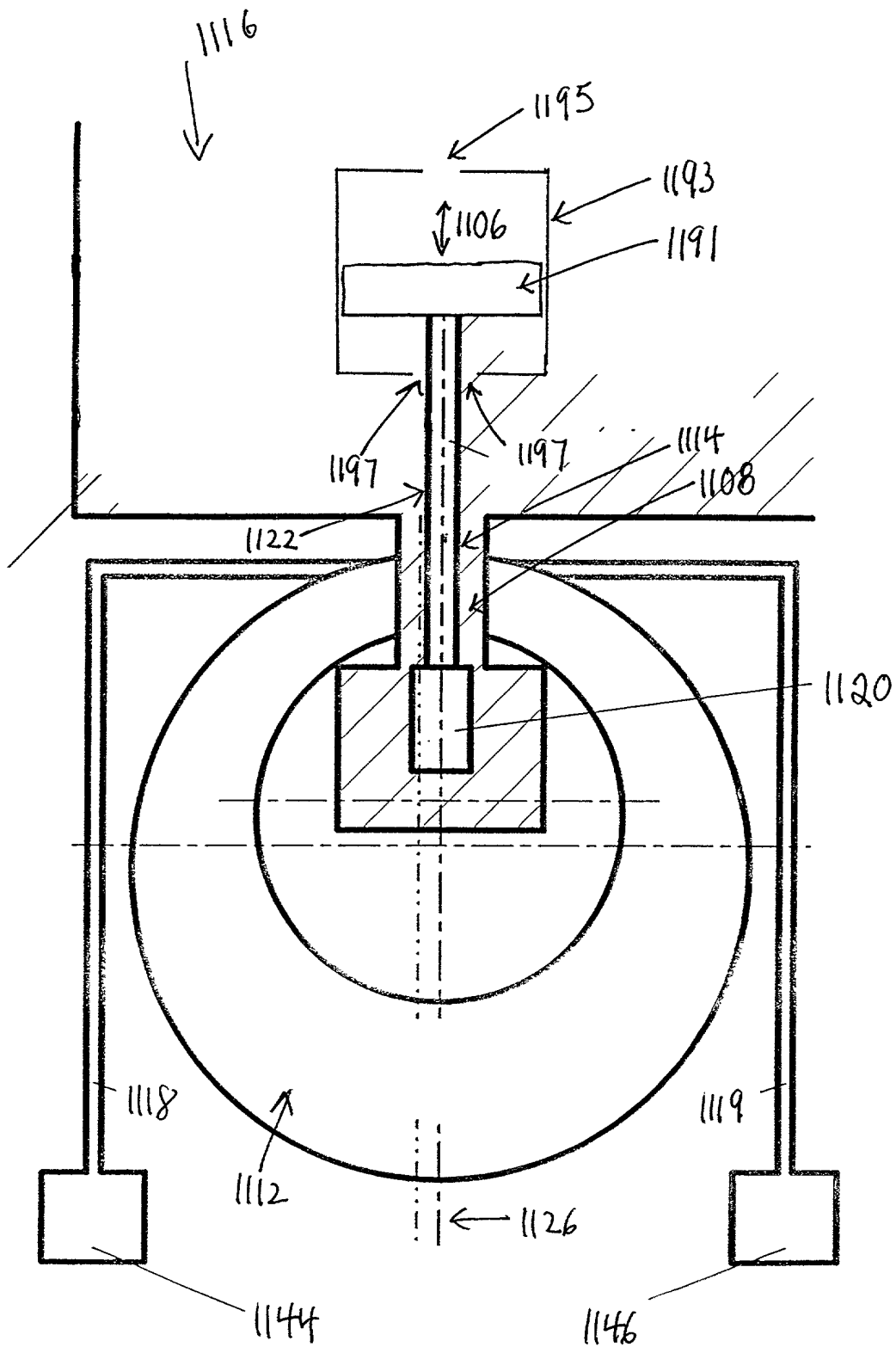


FIG. 16A

2022058662007

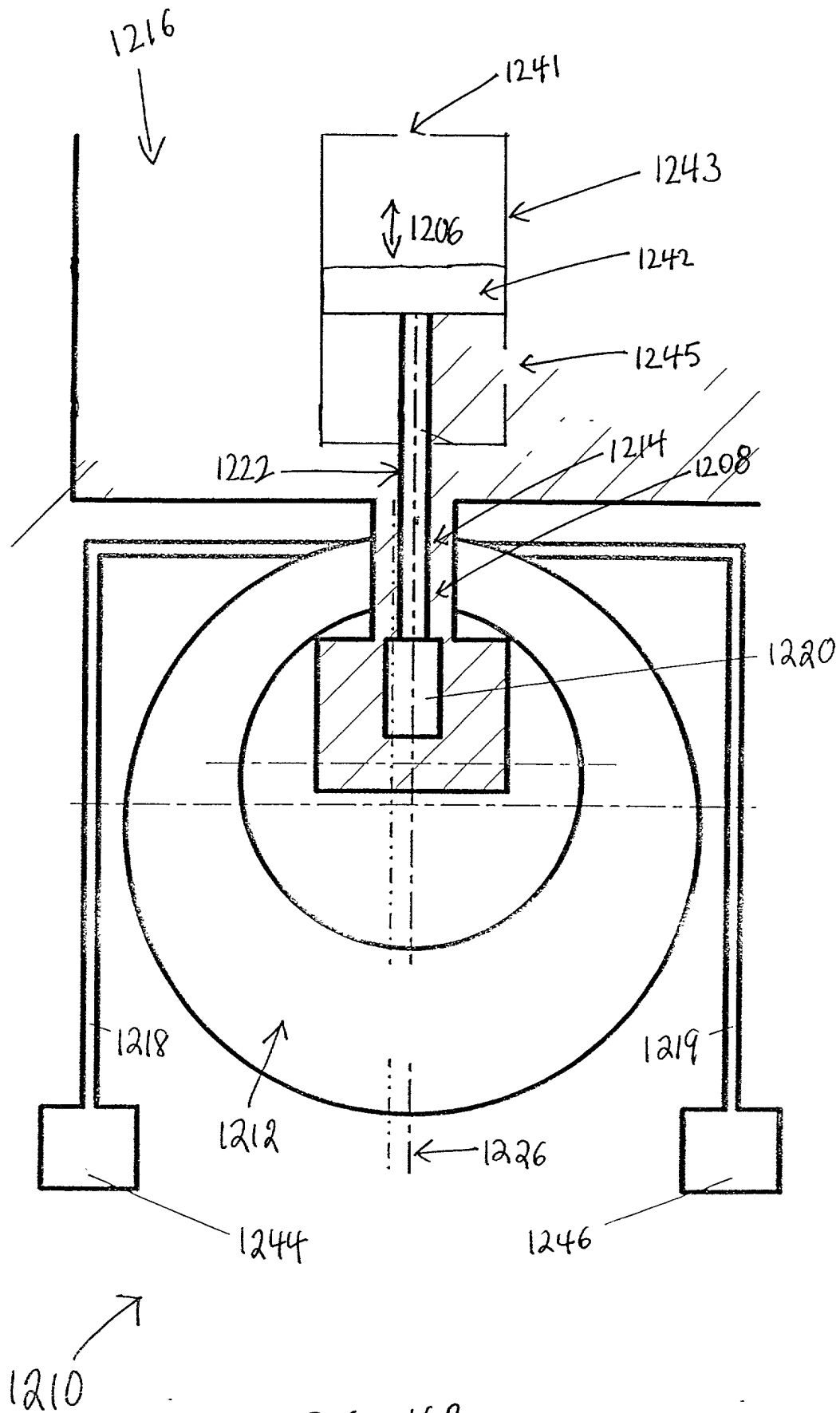


FIG. 16B

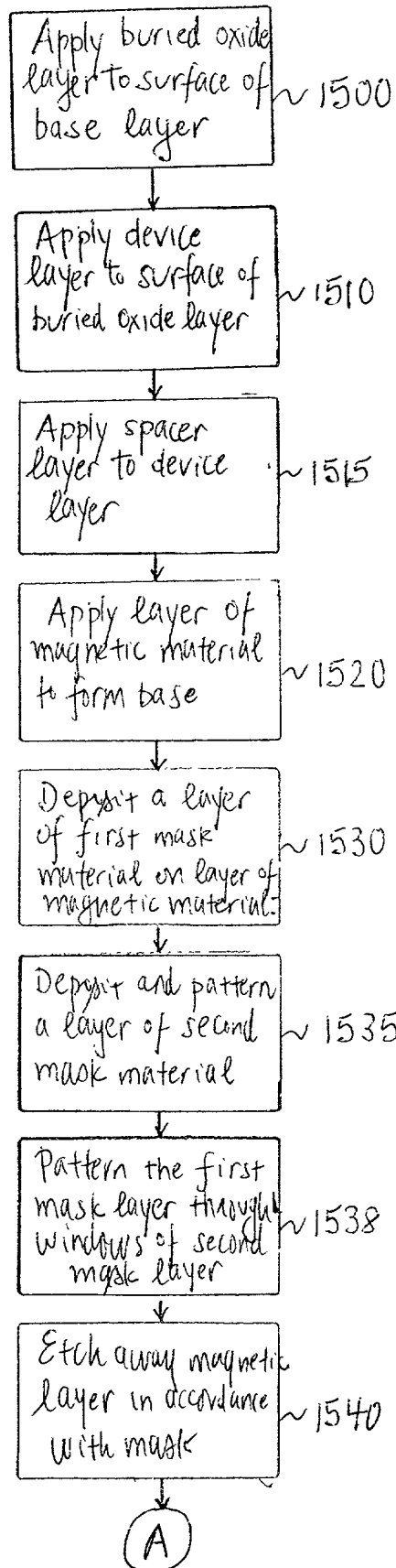


FIG. 17A

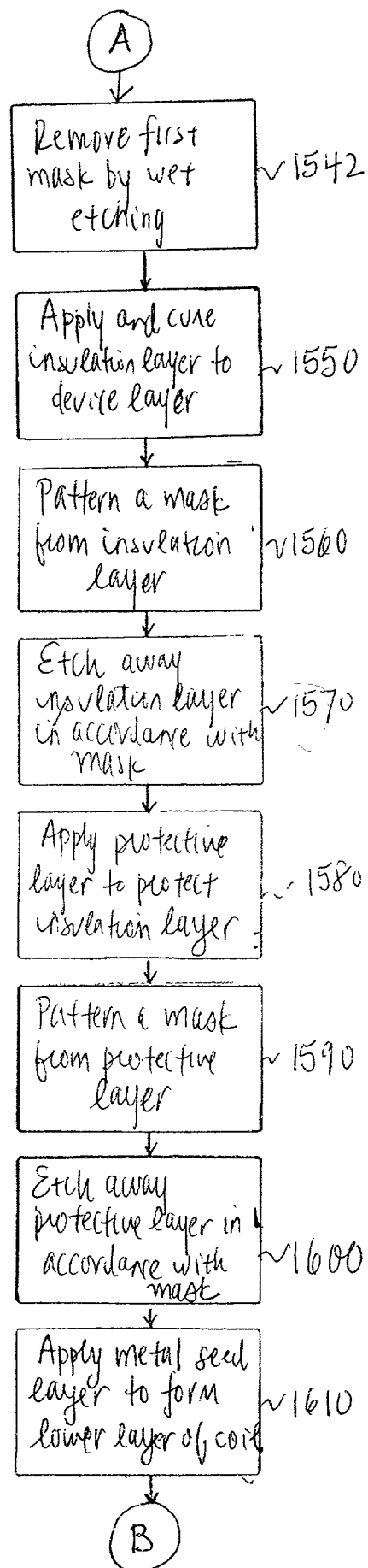


FIG. 17B

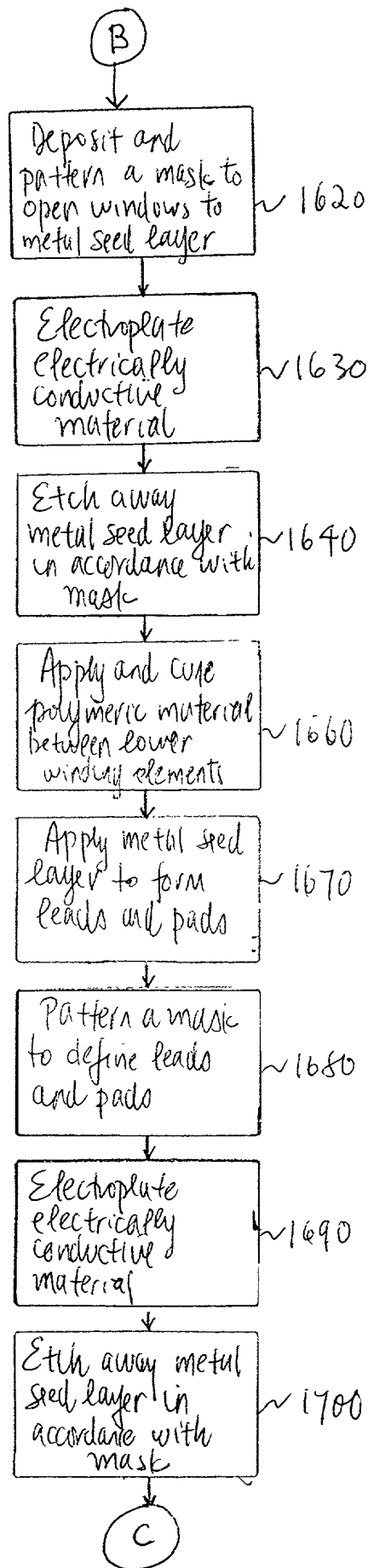


FIG. 17C

	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100
1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100	

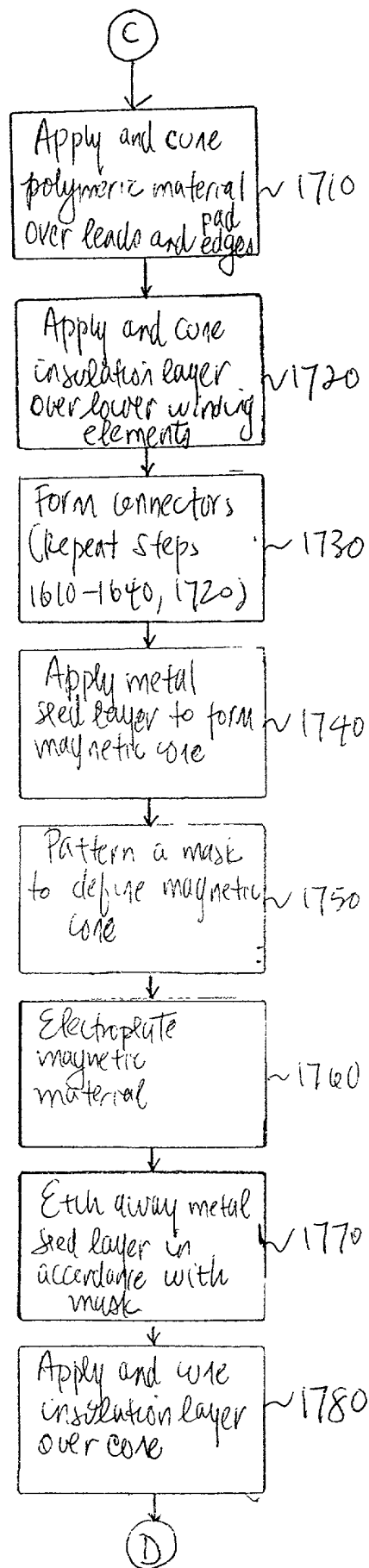


FIG 17D

(D)

Form upper layer
of core and upper
winding elements
(Repeat steps
1610-1660)

~1790

Apply and cure
insulation layer over
upper winding
elements

~1795

Pattern gross
mask

~1800

Repattern gross
mask using mask
of step 1590

~1810

Etch away
protective layer in
conformance with
repatterned mask

~1820

Remove device
layer via deep Si
etching

~1830

Remove buried
oxide layer

~1840

Clean and
dry device

~1850

FIG. 17E